

Title (en)

APPARATUS AND METHOD OF FORMING THIN LAYERS ON SUBSTRATE SURFACES

Title (de)

VORRICHTUNG UND VERFAHREN ZUR AUSBILDUNG DÜNNER SCHICHTEN AUF SUBSTRATOBERFLÄCHEN

Title (fr)

DISPOSITIF ET PROCÉDÉ DE FORMATION DE COUCHES FINES SUR DES SURFACES DE SUBSTRATS

Publication

**EP 2069551 A2 20090617 (DE)**

Application

**EP 07801316 A 20070829**

Priority

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Abstract (en)

[origin: WO2008025352A2] The invention relates to an apparatus and a method of forming thin layers on substrate surfaces. It is an object of the invention to provide possibilities allowing thin layers to be produced on substrate surfaces, exhibiting a defined layered-material formation having desired properties. The apparatus of the invention is designed so that at a reaction chamber region, above a substrate surface to be coated, there is a supply for at least one gaseous precursor that contributes to layer formation. Moreover, a source emitting electromagnetic radiation, which is a plasma source, is disposed in such a way that the electromagnetic radiation emitted effects photolytic activation of atoms and/or molecules of the precursor(s). The plasma source ought to be so disposed, and is also to be operated in such a way, that there is no direct influence of the plasma on the substrate surface and on the precursors that lead to layer formation.

IPC 8 full level

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